

[CIRCUIT CONNECTING STRUCTURE AND FABRICATING METHOD THEREOF]

Abstract

A connecting circuit structure is provided for a circuit carrier . The circuit connecting structure includes at least two insulating layers, two conductive layers, and one conductive pad, wherein a via hole is formed from each of the insulating layers through corresponding insulating layer. One insulating layer is formed over the other. The conductive pad is disposed between the two insulating layers, and two surfaces of the conductive pad are connected to the two via holes respectively. Two conductive layers are respectively formed in the via hole on a same side of the circuit connecting structure in order to connect to the conductive pad respectively. Since a depth/width ratio of the via hole is reduced according to the circuit connecting structure in the present invention, voids and bubbles are effectively avoided and the reliability of fabricating method thereof is increased.